



Material Content Data Sheet



Sales Product Name	IFX25001TS V10			Issued		25. September 2017		
MA#	MA000713292							
Package	PG-TO220-3-1			Weight*		2070.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.945	0.14	0.14	1423	1423
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		118	
	non noble metal	iron	7439-89-6	0.816	0.04		394	
	non noble metal	copper	7440-50-8	815.335	39.38	39.43	393871	394383
wire	non noble metal	aluminium	7429-90-5	0.160	0.01	0.01	77	77
encapsulation	organic material	carbon black	1333-86-4	1.268	0.06		613	
	plastics	epoxy resin	-	58.330	2.82		28178	
	inorganic material	silicondioxide	60676-86-0	574.428	27.75	30.63	277495	306286
leadfinish	non noble metal	tin	7440-31-5	21.462	1.04	1.04	10368	10368
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	118	119
solder	non noble metal	tin	7440-31-5	0.092	0.00		44	
	noble metal	silver	7440-22-4	0.115	0.01		55	
	non noble metal	lead	7439-92-1	4.377	0.21	0.22	2114	2213
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		86	
	non noble metal	iron	7439-89-6	0.590	0.03		285	
	non noble metal	copper	7440-50-8	589.466	28.48	28.52	284760	285131
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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